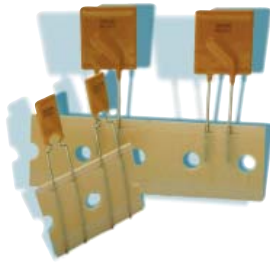


RLD16



16 V

Standard

UL 1434 1st Edition
CSA C22.2 No. 0 CSA TIL No. CA-3A

Approvals (pending)

Features

For automotive and transformer applications with demand for high hold currents

Specifications

Packaging

A* bulk
G tape and reel
F tape and ammo
* preferred type

Materials

Insulating Material: Yellow Epoxy
UL 94 V-0
Round Pins: Copper, tin plated

Max. Device Surface Temperature in Tripped State

125 °C

Operating / Storage Temperature

-40 °C to +85 °C (consider derating)

Humidity Ageing

+85 °C, 85 % R.H., 1000 hours, ± 5 % typical resistance change

Soldering Characteristics

Solderability per MIL-STD-202, Method 208E

Thermal Shock

MIL-STD-202F, Method 107G
+125 °C to -40 °C 10 times, ± 5 % typical resistance change

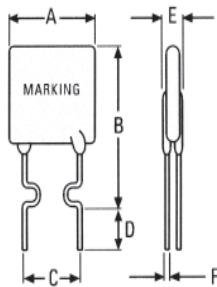
Solvent Resistance

MIL-STD-202, Method 215F, no change

Marking

"P", voltage, amperage rating, lot number

Dimensions (mm)



Dimensions (mm)										
Model	A	B	C	D	E	Physical Characteristics		packaging quantity		
	Max	Max	typ	Min	Max	Lead	Material	bag	ammo	
RLD16P700G	14.0	19.7	5.1	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000	
RLD16P900G	14.0	21.7	5.1	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000	
RLD16P1100G	19.1	26.0	5.1	7.6	3.0	0.81 dia.	Sn/Cu	100	1,000	
RLD16P1400G	23.5	27.9	10.2	7.6	3.0	1.00 dia.	Sn/Cu	100	-	

Permissible continuous operating current is ≤ 100 % at ambient temperature of 20 °C (68 °F).										
Model	I _{hold}	I _{Trip}	V _{max,dc}	I _{max}	max. time to trip	P _{d,max}	Resistance		Approvals	
	(A)	(A)	(V)	(A)	(s @ A)	(W)	R _{min} (Ω)	R _{I,max} (Ω)	cURus	TÜV
RLD16P700G	7	11.9	16	100	3.5 @ 35	3.0	0.0077	0.02	p	p
RLD16P900G	9	15.3	16	100	5.5 @ 45	3.3	0.0047	0.0135	p	p
RLD16P1100G	11	18.7	16	100	7.0 @ 55	3.7	0.0037	0.0089	p	p
RLD16P1400G	14	23.8	16	100	9.0 @ 70	4.6	0.0026	0.0064	p	p

NOTE:

I_{hold} = Hold current: maximum current device will pass without tripping in 20 °C still air.
I_{Trip} = Trip current: minimum current at which the device will trip in 20 °C still air.
V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})
I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

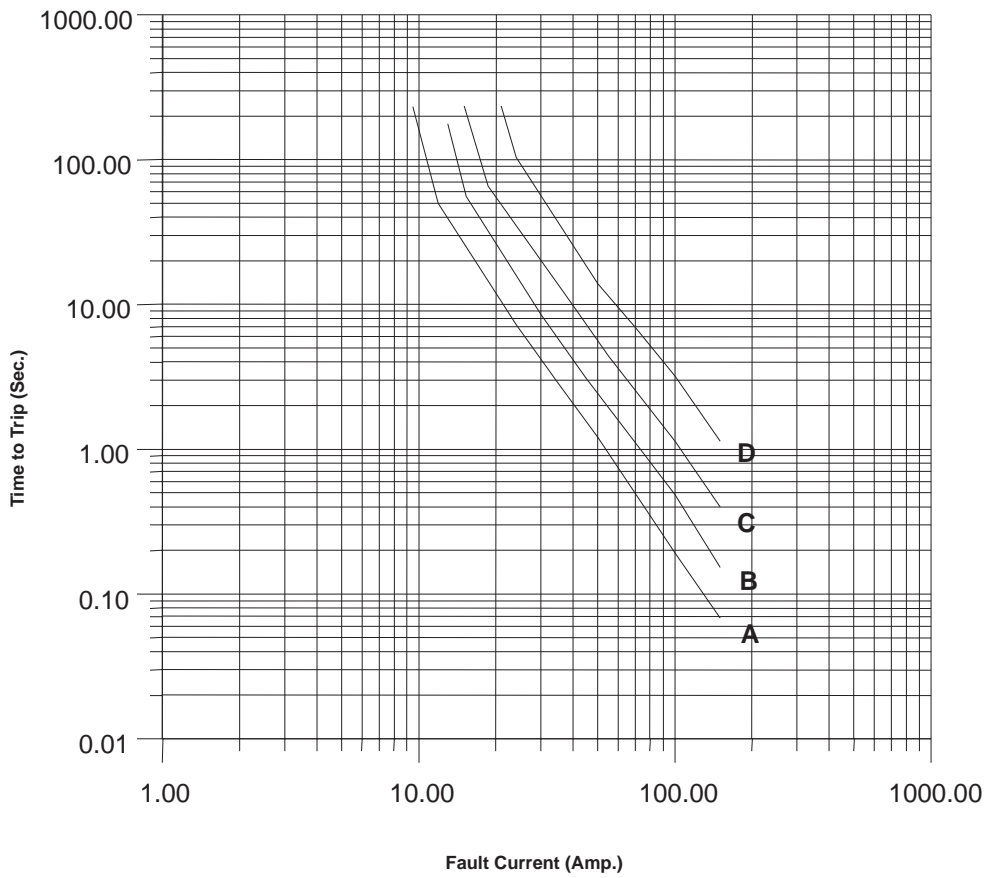
P_d = Power dissipated from device when in the tripped state at 20 °C still air.
R_{min} = Minimum resistance of device in initial (un-soldered) state.
R_{I,max} = Maximum resistance of device at 20 °C measured one hour after tripping for 20 s.
Caution: Operation beyond the specified rating may result in damage and possible arcing and flame. Specifications are subject to change without notice

Order Information

Qty.	Order-Number	Model	*	Packaging
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* optional "F" for lead free devices

RLD16



- A: RLD16P700G
- B: RLD16P900G
- C: RLD16P1100G
- D: RLD16P1400G

Thermal Derating Chart

Model	Ambient Operation Temperature - I_{hold} (A)								
	-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
RLD16P700G	10.4	9.3	8.2	7.0	6.1	5.6	5.0	4.5	3.7
RLD16P900G	13.3	12.0	10.6	9.0	7.8	7.1	6.5	5.8	4.7
RLD16P1100G	16.3	14.6	12.9	11.0	9.6	8.7	7.9	7.0	5.8
RLD16P1400G	20.7	18.6	16.5	14.0	12.2	11.1	10.0	9.0	7.4